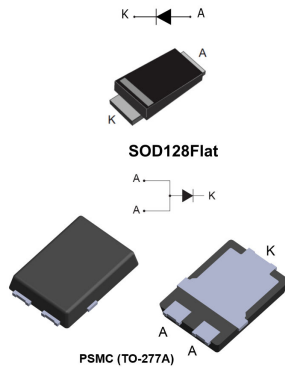



## Automotive 100 V - 5 A power Schottky trench rectifier



### Features

- AEC-Q101 qualified 
- PPAP capable
- Low forward voltage drop
- Low recovery charges
- Reduces conduction, reverse and switching losses
- 100% Avalanche tested in production
- Operating  $T_j$  from  $-40\text{ }^{\circ}\text{C}$  to  $+175\text{ }^{\circ}\text{C}$
- Flat packages
- ECOPACK2 compliant

### Applications

- Automotive LED lighting
- Flyback topology
- On-board DC/DC converter
- ECU power supply



#### Product label



#### Product status link

[STPST5H100-Y](#)

### Description

This 5 A, 100 V rectifier is based on ST trench technology that achieves the best-in-class  $V_F/I_R$  trade-off for a given silicon surface.

Integrated in flat and space-saving packages, this STPST5H100-Y trench, and automotive-graded device is intended to be used in high frequency miniature switched mode power supplies such as in automotive, DC/DC converters or ECU power supply. It is also adapted to freewheeling applications, OR-ring, or reverse polarity protection.

#### Product summary

$I_{F(AV)}$	5 A
$V_{RRM}$	100 V
$T_j$ (max.)	175 $^{\circ}\text{C}$
$V_F$ (typ.)	0.550 V

# 1 Characteristics

**Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified, with 2 anode terminals short-circuited)**

Symbol	Parameter			Value	Unit
V <sub>RRM</sub>	Repetitive peak reverse voltage (T <sub>j</sub> = -40°C to + 175°C)			100	V
I <sub>F(AV)</sub>	Average forward current, δ = 0.5, square wave	SOD128Flat	T <sub>L</sub> = 120 °C	5	A
		PSMC (TO-277)	T <sub>c</sub> = 160 °C		
I <sub>FSM</sub>	Surge non repetitive forward current	SOD128Flat	t <sub>p</sub> = 10 ms sinusoidal	75	A
		PSMC (TO-277)		155	
I <sub>AS</sub>	Single pulse avalanche current <sup>(1)</sup>	T <sub>j</sub> = 25°C, L = 300 μH, V <sub>DD</sub> = 15 V		9	A
T <sub>stg</sub>	Storage temperature range			-65 to +175	°C
T <sub>j</sub>	Maximum operating junction temperature range <sup>(2)</sup>			-40 to +175	°C

1. Please refer to [Figure 1](#) and [Figure 2](#) for the unclamped inductive switching test circuit, and waveform.
2.  $(dP_{tot}/dT_J) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

**Table 2. Thermal resistance parameter**

Symbol	Parameter		Typ. value	Unit
$R_{th(j-l)}$	Junction to lead	SOD128Flat	10	$^{\circ}\text{C/W}$
$R_{th(j-c)}$	Junction to case	PSMC (TO-277)	1.8	

For more information, please refer to the following application note:

- [AN5088](#): Rectifiers thermal management, handling and mounting recommendations

**Table 3. Static electrical characteristics**

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_J = 125^{\circ}\text{C}$	$V_R = 70\text{ V}$	-	1.0	3.2	mA
		$T_J = 25^{\circ}\text{C}$	$V_R = 100\text{ V}$	-		11.5	$\mu\text{A}$
		$T_J = 125^{\circ}\text{C}$		-	2.0	6.5	mA
$V_F^{(2)}$	Forward voltage drop	$T_J = 25^{\circ}\text{C}$	$I_F = 2.5\text{ A}$	-	0.520	0.580	V
		$T_J = 125^{\circ}\text{C}$		-	0.450	0.510	
		$T_J = 25^{\circ}\text{C}$	$I_F = 5\text{ A}$	-	0.615	0.680	
		$T_J = 125^{\circ}\text{C}$		-	0.550	0.605	

1. Pulse test:  $t_p = 5\text{ ms}$ ,  $\delta < 2\%$
2. Pulse test:  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

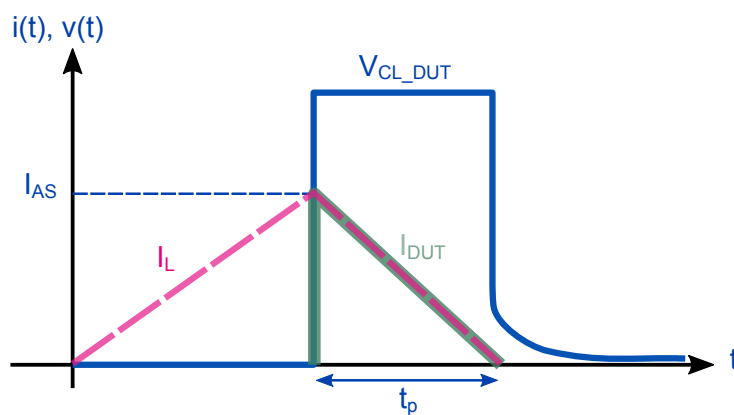
To evaluate the conduction losses, use the following equation:

$$P = 0.415 \times I_{F(AV)} + 0.038 \times I_F^2(\text{RMS})$$

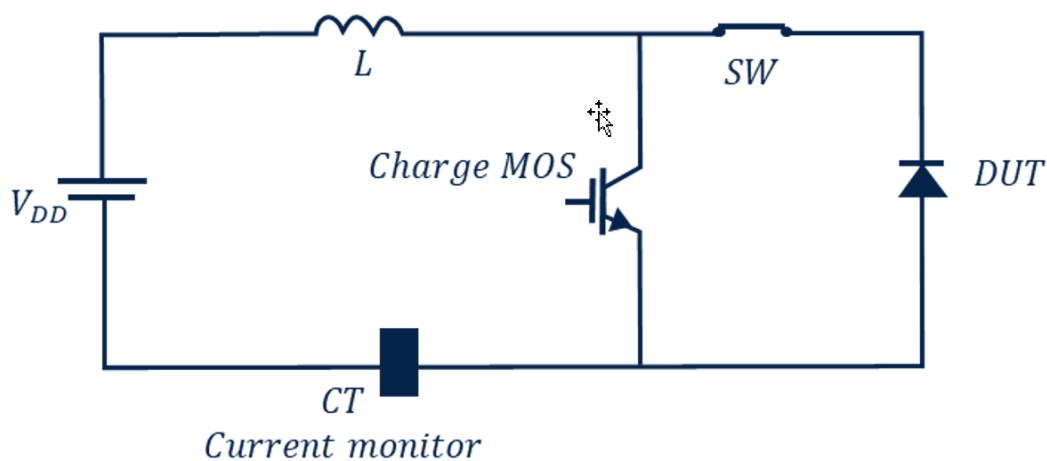
For more information, please refer to the following application notes related to the power losses :

- [AN604](#): Calculation of conduction losses in a power rectifier
- [AN4021](#): Calculation of reverse losses on a power diode

**Figure 1.** Current and voltage waveforms for avalanche energy test across D.U.T (device under test)



**Figure 2.** Unclamped Inductive Switching Test circuit

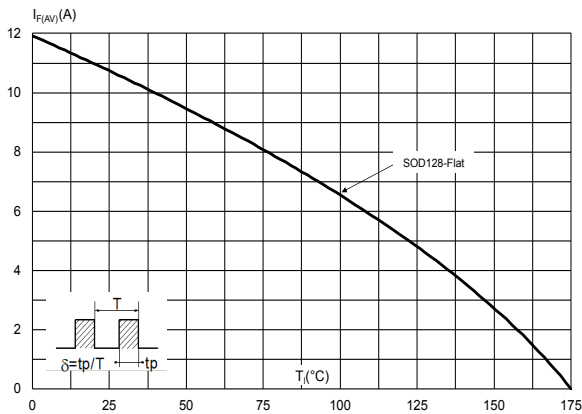


$$E_{AS} = \frac{1}{2} \times L \times I_{AS}^2 \times \left( \frac{V_{CLDUT}}{V_{CLDUT} - V_{DD}} \right) \cong \frac{1}{2} \times L \times I_{AS}^2$$

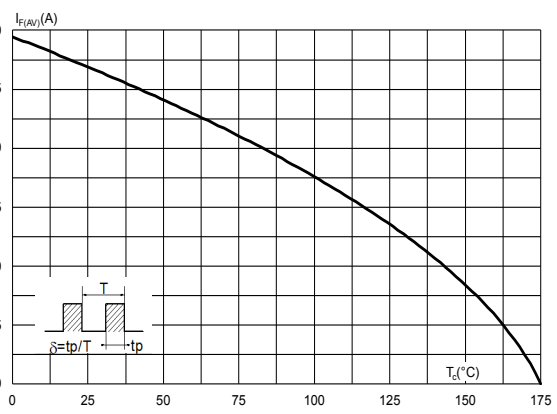
$$t_p = \left( \frac{L \times I_{AS}}{V_{CLDUT} - V_{DD}} \right)$$

## 1.1 Characteristics (curves)

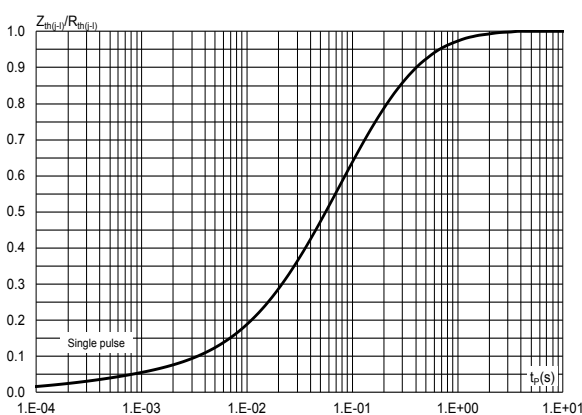
**Figure 3. Average forward current versus lead temperature ( $\delta = 0.5$ , SOD128Flat)**



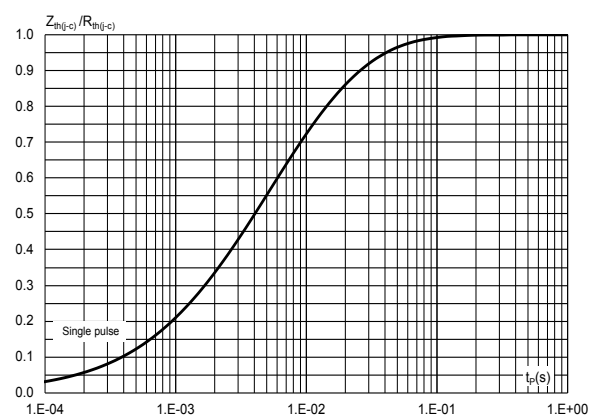
**Figure 4. Average forward current versus case temperature ( $\delta = 0.5$ , PSMC)**



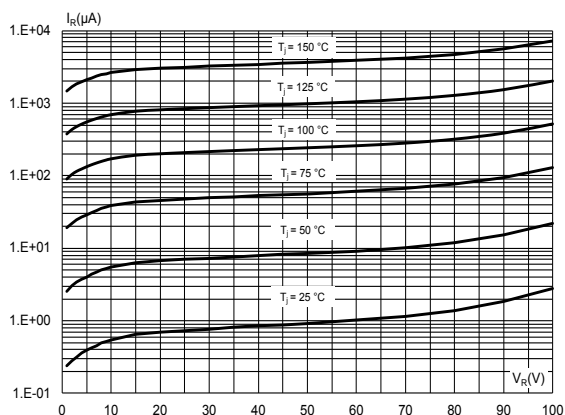
**Figure 5. Relative variation of thermal impedance junction to lead versus pulse duration (SOD128Flat)**



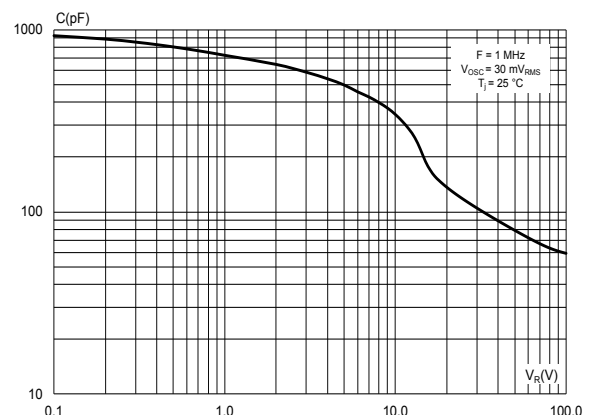
**Figure 6. Relative variation of thermal impedance junction to case versus pulse duration (PSMC)**



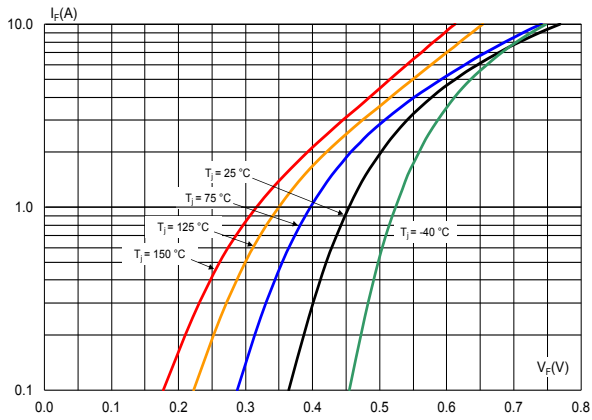
**Figure 7. Reverse leakage current versus reverse voltage applied (typical values)**



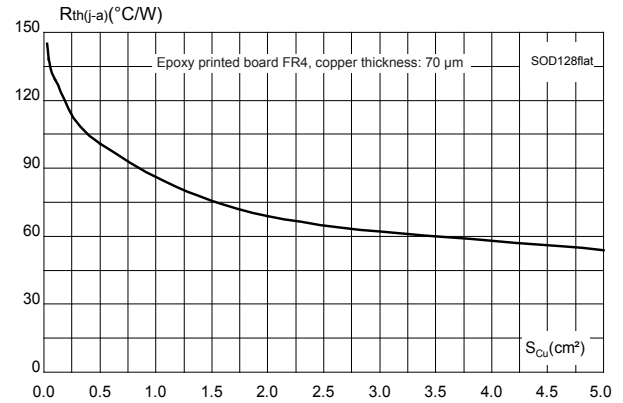
**Figure 8. Junction capacitance versus reverse voltage applied (typical values)**



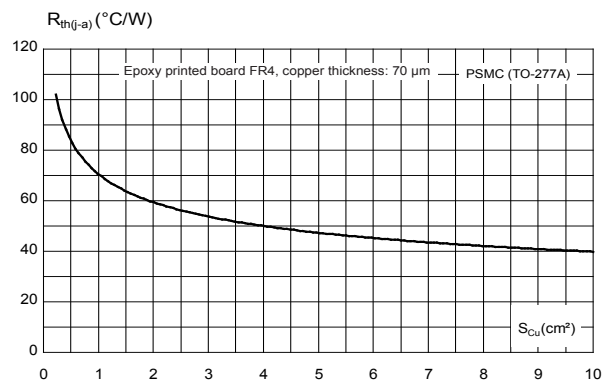
**Figure 9. Forward voltage drop versus forward current (typical values)**



**Figure 10. Thermal resistance junction to ambient versus copper surface under each lead (typical values, epoxy printed board FR4,  $e_{Cu} = 70 \mu m$ )**



**Figure 11. Thermal resistance junction to ambient versus copper surface under tab (typical values, epoxy printed board FR4,  $e_{Cu} = 70 \mu m$ )**



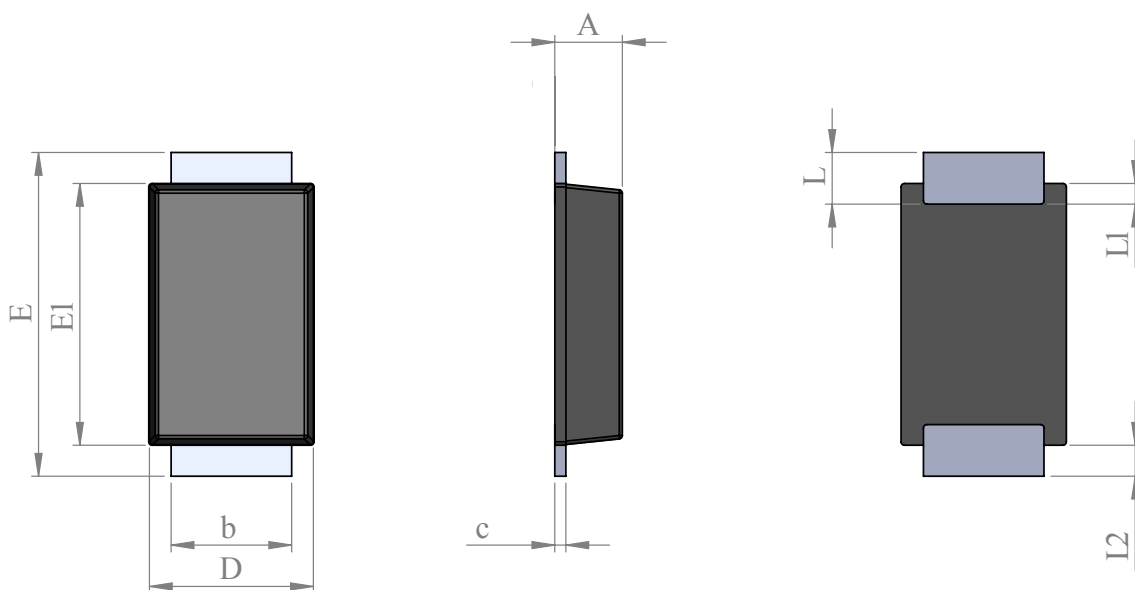
## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 2.1 SOD128Flat package information

- Lead-free package

**Figure 12. SOD128Flat package outline**

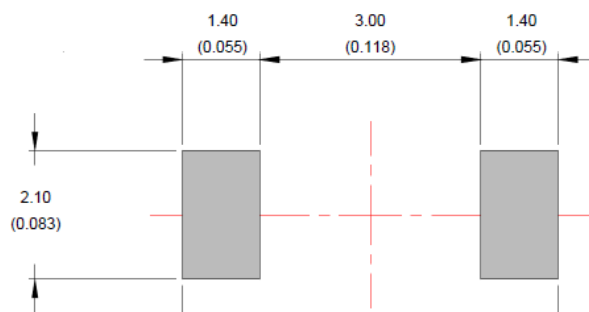


**Note:** This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

**Table 4. SOD128Flat package mechanical data**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.93	1.03	0.037	0.041
b	1.69	1.81	0.067	0.071
c	0.10	0.22	0.004	0.009
D	2.30	2.50	0.091	0.098
E	4.60	4.80	0.181	0.189
E1	3.70	3.90	0.146	0.154
L	0.55	0.85	0.026	0.033
L1	0.30 typ.		0.012 typ.	
L2	0.45 typ.		0.018 typ.	

**Figure 13. SOD128Flat footprint in mm (inches)**

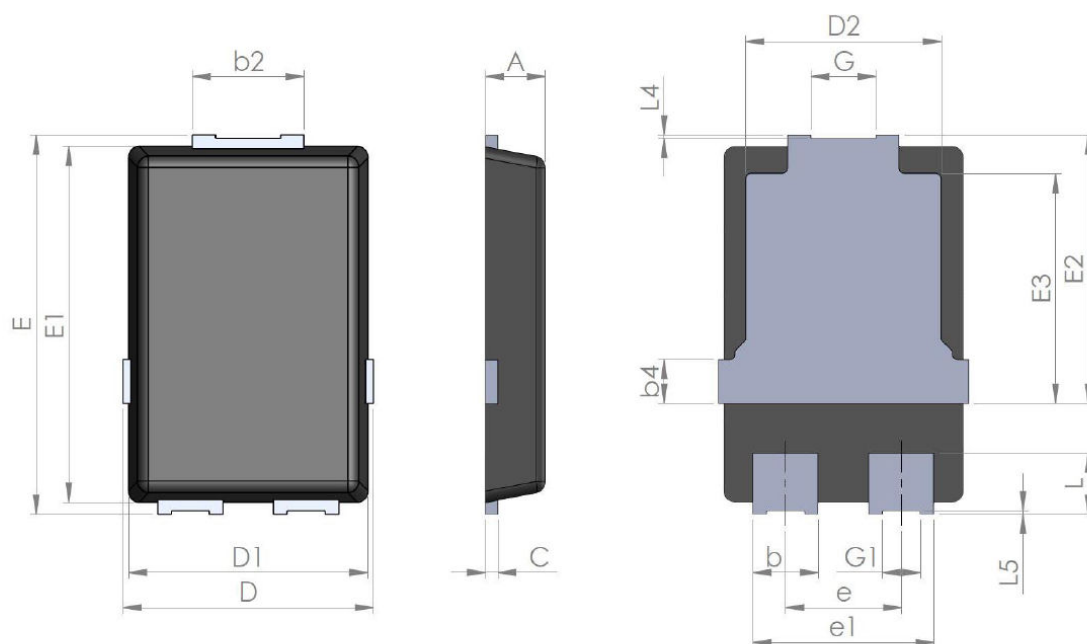


**Note:** For package and tape orientation, reel and inner box dimensions and tape outline please check [TN1173](#).

## 2.2 PSMC (TO-277A) package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)

Figure 14. PSMC (TO-277A) package outline

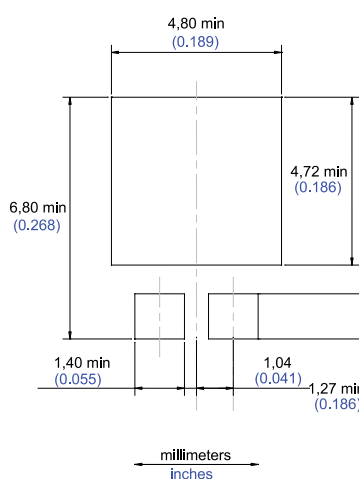


**Note:** This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.



**Table 5. PSMC (TO-277A) package mechanical data**

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.00	1.10	1.20	0.039	0.043	0.047
b	1.05	1.20	1.35	0.041	0.047	0.053
b2	1.90	2.05	2.20	0.075	0.081	0.087
b4		0.75			0.029	
C	0.15	0.23	0.40	0.006	0.009	0.016
D	4.45	4.60	4.75	0.175	0.181	0.187
D1	4.25	4.40	4.45	0.167	0.173	0.175
D2	3.40	3.60	3.70	0.134	0.142	0.146
E	6.35	6.50	6.65	0.250	0.256	0.262
E1	6.05	6.10	6.15	0.238	0.240	0.242
E2	4.50	4.60	4.70	0.177	0.181	0.185
E3		3.94			1.55	
e		2.13			0.084	
e1		3.33			0.131	
G		1.20			0.047	
G1		0.70			0.027	
L	0.90	1.05	1.24	0.035	0.041	0.049
L4	0.02			0.0008		
L5	0.02			0.0008		

**Figure 15. PSMC (TO-277A) package footprint in mm (in inches)**


**Note:** For package and tape orientation, reel and inner box dimensions and tape outline please check [TN1173](#).



### 3 Ordering information

**Table 6. Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPST5H100AFY	T5H1Y	SOD128Flat	26.4 mg	3000	Tape and reel
STPST5H100SFY		PSMC (TO-277A)	90.0 mg	6000	

## Revision history

Table 7. Document revision history

Date	Revision	Changes
02-Jan-2023	1	Initial release.
26-May-2023	2	Updated <a href="#">Figure 12</a> .
21-Jul-2023	3	Updated <i>Features</i> .

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